	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2023-06-08 2023-06-08 2023-06-08 2023-06-08 Product Enviro Compliance NA Product-Env-Stewards Authorized Representative* Product-Env-Stewards Prod	752-21.1										als and M	fg Informati	ion			
Semilar Contact Name Title - Contact Phone - Contact* Phone - Representative*	upplier Inform	ation						<u>.</u>			, <u>U</u>					
Title - Contact Name Product Envi-Stewards Product Envi-Compliance Product Envi-Stewards Product Envi-Stewards Product Envi-Stewards Product Envi-Stewards Product Envi-Compliance NA Product-Env-Stewards Product-E	company name*		Company unique ID			ī	Unique ID Authority					Response Date*				
Product-Env-Stewards	nsemi												2023-06-08			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Requester Item Number Remail - Representative* Requester Item Number Remail - Representative* Requester Item Number Representative* Requester Item Number Requester Item Number Remail - Representative* Requester Item Number Representative* Requester Item Number Representative* Requester Item Number Representative* Requester Item Number Request	ontact Name			Title - Conta	Title - Contact			Phone - Contact*					Email - Contact*			
Product Envi- Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit Unit Unit Version Manufacturing Site Weight* Weight* Nome of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewar	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	uthorized Represen	ntative*	Title - Representative]	Phone - Representative*				Email - Representative*					
EMI4192MTTAG LOW RESISTANCE CMF W ESD 2023-06-08 9.580241 mg Each	Product-Env-Stewar	rds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date Version 1		Manufacturing Site		1	Weight*	UOM	Unit Type	
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			EMI4192	MTTAG	LOW RESISTANC	CE CMF W E	SD	2023-06-08					ç	0.580241	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Daga	Alloy	STD 020 MS	I Dating	Dook Pro	anns Pady	Tomporet	May Timo	at Dook	Tomporet	ura Numb	par of Paflow Cy	alac
omments	2 2			·		L Kanng								ber of Reflow Cyc	cies	
	•	i (Sii) - anneaied	C	O Alloy	1			200		JC			secon	us 3		
ver 1 - maximum ume at peak temperature during soldering is 10-50 seconds		me at neak townst	o dunina1	domina ia 10 '	20 sacands											
or more information regarding material composition please refer to page 3																

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.990241	mg	Supplier	Silicon (Si)	7440-21-3		0.9902	mg
Die Attach Epoxy	0.11	mg		Epoxy resin	proprietary data		0.033	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0385	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0385	mg
Lead Frame	2.2	mg	Supplier	Zinc (Zn)	7440-66-6		0.0022	mg
			Supplier	Iron (Fe)	7439-89-6		0.0506	mg
			Supplier	Copper (Cu)	7440-50-8		2.145	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0022	mg
Mold Compound-Black	5.59	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.4472	mg
			Supplier	Carbon Black (C)	1333-86-4		0.028	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.1118	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.8354	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1677	mg
Plating	0.04	mg	Supplier	Silver (Ag)	7440-22-4		0.0027	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0029	mg
			В	Nickel (Ni)	7440-02-0		0.0339	mg
			Supplier	Gold (Au)	7440-57-5		0.0004	mg
Protection coat	0.57	mg		Polyimide	proprietary data		0.57	mg
Wire Bond - Au	0.08	mg	Supplier	Gold (Au)	7440-57-5		0.08	mg